

## HIGH VOLTAGE FAST-SWITCHING NPN POWER TRANSISTOR

- SGS-THOMSON PREFERRED SALES TYPE
- NPN TRANSISTOR
- HIGH VOLTAGE CAPABILITY
- LOW SPREAD OF DYNAMIC PARAMETERS
- MINIMUM LOT-TO-LOT SPREAD FOR RELIABLE OPERATION
- VERY HIGH SWITCHING SPEED

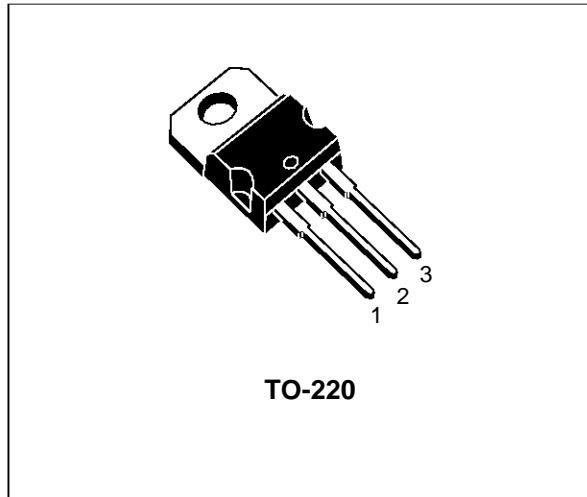
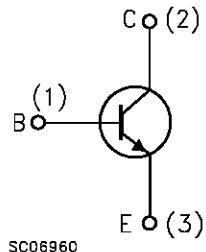
**APPLICATIONS:**

- ELECTRONIC BALLASTS FOR FLUORESCENT LIGHTING

**DESCRIPTION**

The device is manufactured using high voltage Multi Epitaxial Planar technology for high switching speeds and medium voltage capability. It uses a Cellular Emitter structure with planar edge termination to enhance switching speeds while maintaining the wide RBSOA.

The device is designed for use in lighting applications and low cost switch-mode power supplies. BUL128 is offered as the standard device. Storage time groupings are available upon request.


**INTERNAL SCHEMATIC DIAGRAM**

**ABSOLUTE MAXIMUM RATINGS**

Symbol	Parameter	Value	Unit
$V_{CES}$	Collector-Emitter Voltage ( $V_{BE} = 0$ )	700	V
$V_{CEO}$	Collector-Emitter Voltage ( $I_B = 0$ )	400	V
$V_{EBO}$	Emitter-Base Voltage ( $I_C = 0$ )	9	V
$I_C$	Collector Current	4	A
$I_{CM}$	Collector Peak Current ( $t_p < 5 \text{ ms}$ )	8	A
$I_B$	Base Current	2	A
$I_{BM}$	Base Peak Current ( $t_p < 5 \text{ ms}$ )	4	A
$P_{tot}$	Total Dissipation at $T_c = 25^\circ\text{C}$	70	W
$T_{stg}$	Storage Temperature	-65 to 150	$^\circ\text{C}$
$T_j$	Max. Operating Junction Temperature	150	$^\circ\text{C}$

## THERMAL DATA

R <sub>thj-case</sub>	Thermal Resistance Junction-Case	Max	1.78	°C/W
R <sub>thj-amb</sub>	Thermal Resistance Junction-Ambient	Max	62.5	°C/W

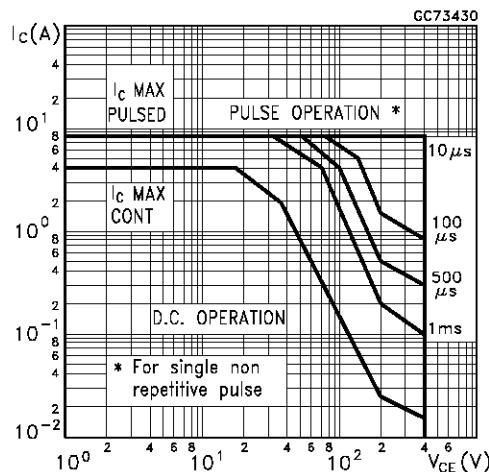
ELECTRICAL CHARACTERISTICS ( $T_{case} = 25$  °C unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
I <sub>CES</sub>	Collector Cut-off Current ( $V_{BE} = -1.5$ V)	$V_{CE} = 700$ V $V_{CE} = 700$ V $T_j = 125$ °C			100 500	μA μA
V <sub>EBO</sub>	Emitter-Base Voltage	$I_E = 10$ mA	9			V
V <sub>CEO(sus)</sub>	Collector-Emitter Sustaining Voltage	$I_C = 100$ mA      L = 25 mH	400			V
I <sub>CEO</sub>	Collector Cut-Off Current ( $I_B = 0$ )	$V_{CE} = 400$ V			250	μA
V <sub>CE(sat)*</sub>	Collector-Emitter Saturation Voltage	$I_C = 0.5$ A $I_B = 0.1$ A $I_C = 1$ A $I_B = 0.2$ A $I_C = 2.5$ A $I_B = 0.5$ A $I_C = 4$ A $I_B = 1$ A		0.5	0.7 1 1.5	V V V V
V <sub>BE(sat)*</sub>	Base-Emitter Saturation Voltage	$I_C = 0.5$ A $I_B = 0.1$ A $I_C = 1$ A $I_B = 0.2$ A $I_C = 2.5$ A $I_B = 0.5$ A			1.1 1.2 1.3	V V V
$h_{FE}^*$	DC Current Gain	$I_C = 10$ mA $V_{CE} = 5$ V $I_C = 2$ A $V_{CE} = 5$ V	10 8		40	
t <sub>s</sub> t <sub>f</sub>	RESISTIVE LOAD Storage Time Fall Time	$V_{CC} = 125$ V $I_C = 2$ A $I_{B1} = 0.4$ A $I_{B2} = -0.4$ A $T_p = 30$ μs (see fig.2)		2.5 0.2	3 0.4	μs μs
t <sub>s</sub> t <sub>f</sub>	INDUCTIVE LOAD Storage Time Fall Time	$I_C = 2$ A $I_{B1} = 0.4$ A $V_{BEoff} = -5$ V $R_{BB} = 0$ Ω $V_{clamp} = 200$ V (see fig.1)		0.6 0.1	1 0.2	μs μs

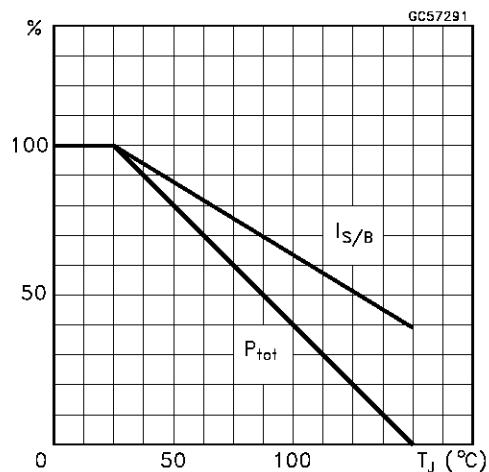
\* Pulsed: Pulse duration = 300 μs, duty cycle 1.5 %

Ordering information: Standard device, BUL128; storage time grouping, available upon request.

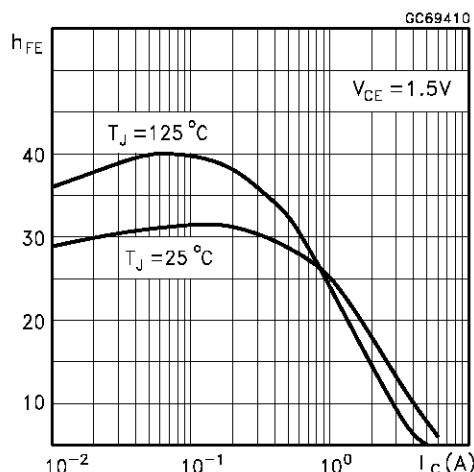
## Safe Operating Areas



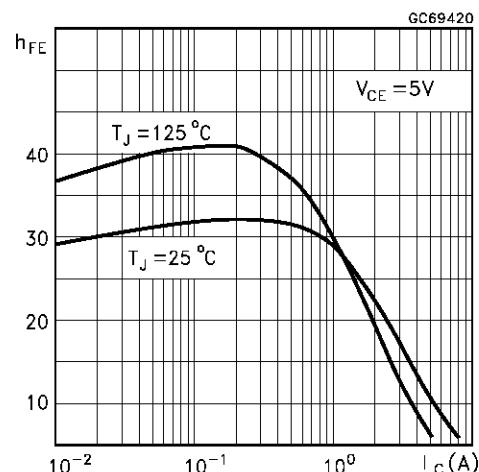
## Derating Curve



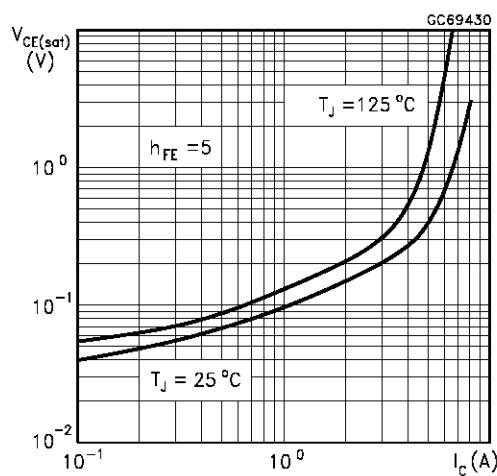
## DC Current Gain



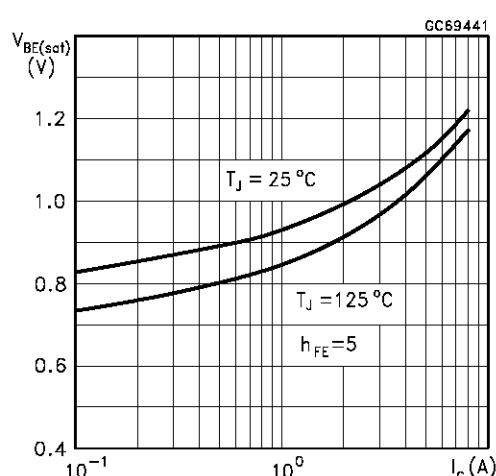
## DC Current Gain



## Collector Emitter Saturation Voltage

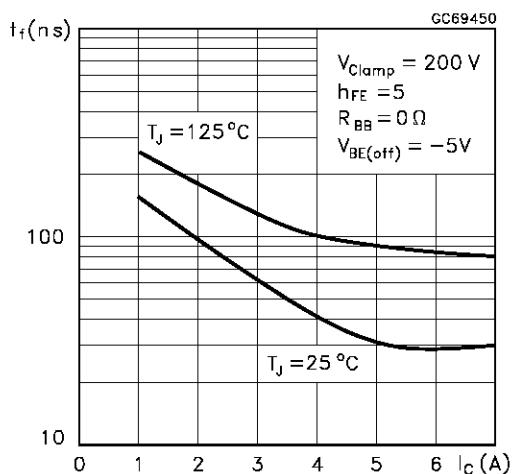


## Base Emitter Saturation Voltage

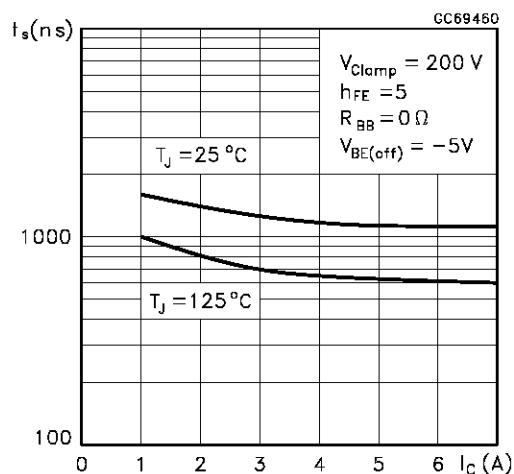


## BUL128

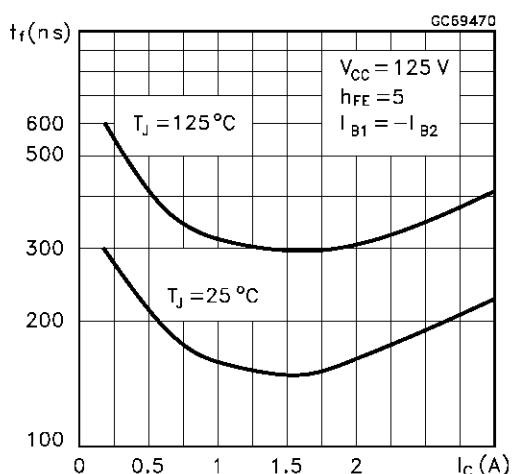
Inductive Fall Time



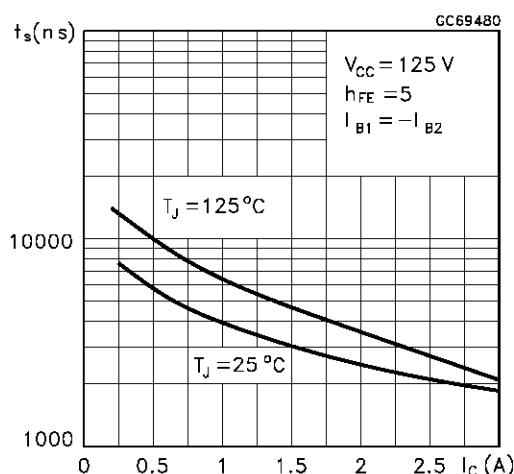
Inductive Storage Time



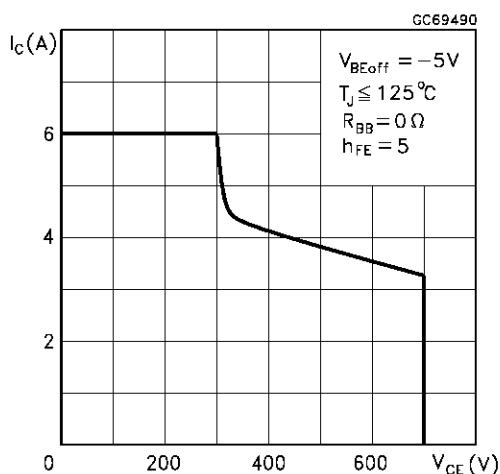
Resistive Fall Time

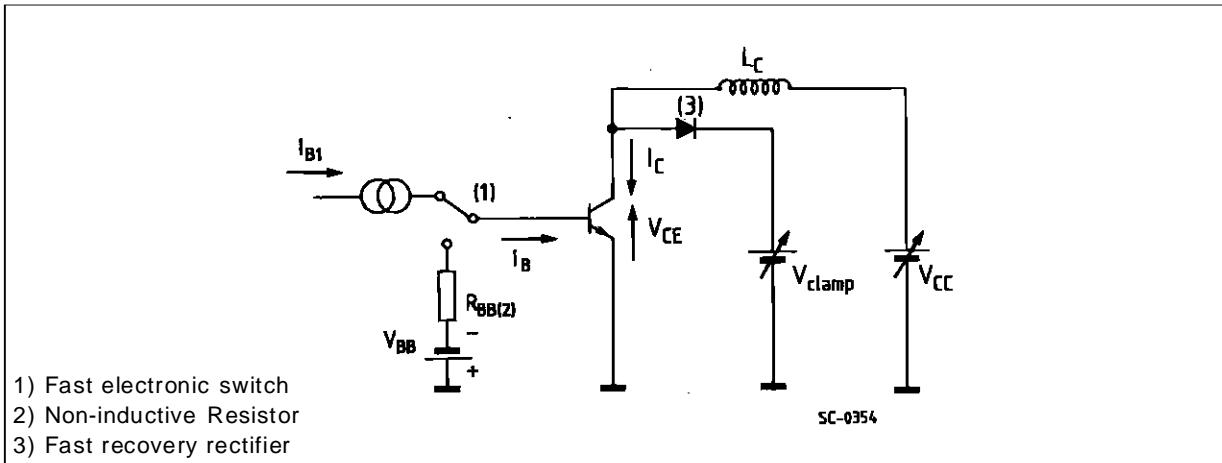
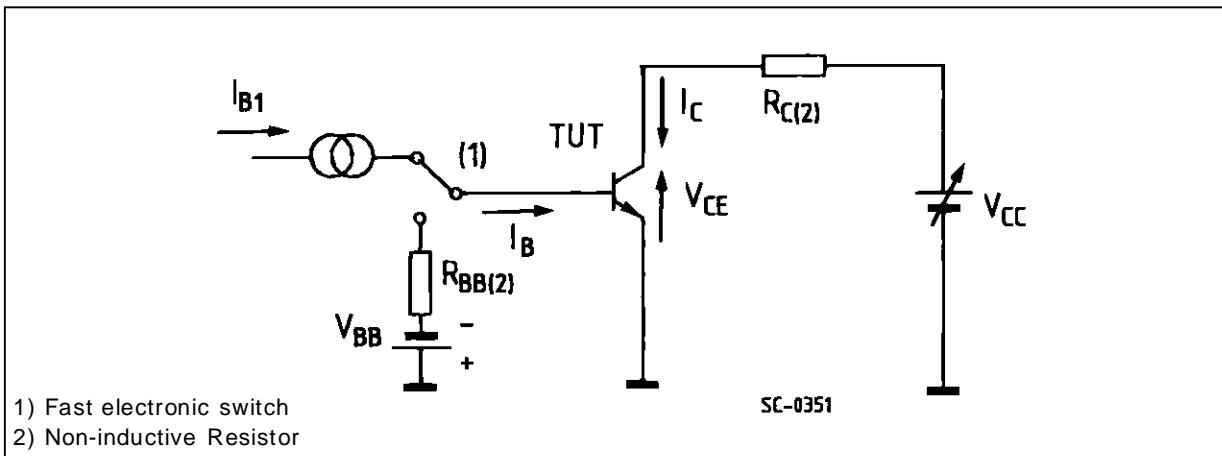


Resistive Load Storage Time



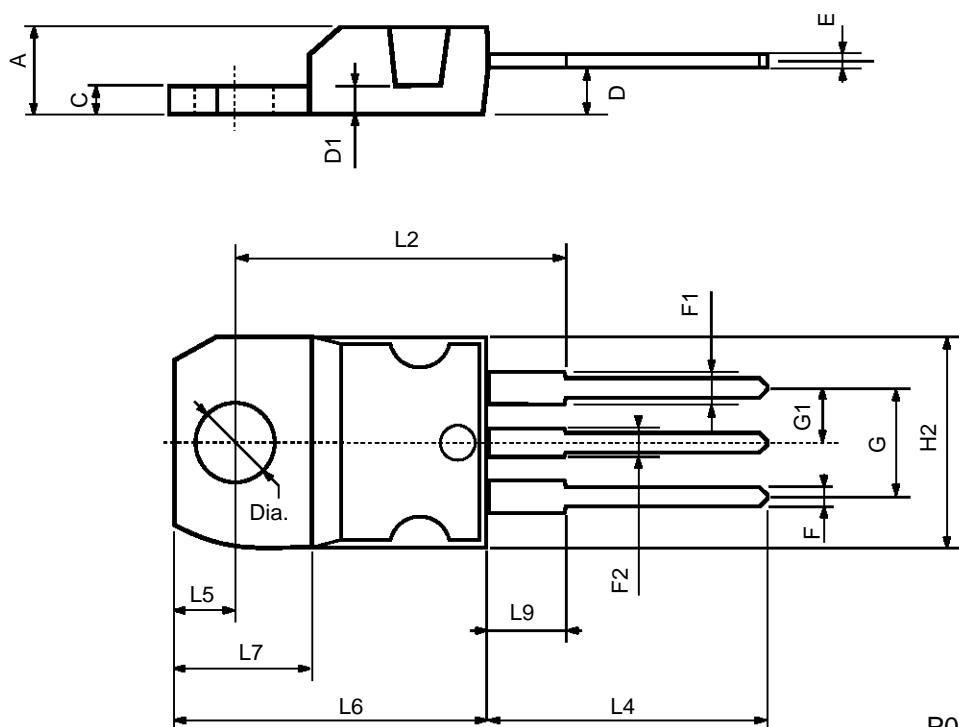
Reverse Biased SOA



**Figure 1:** Inductive Load Switching Test Circuit.**Figure 2:** Resistive Load Switching Test Circuit.

## TO-220 MECHANICAL DATA

DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	4.40		4.60	0.173		0.181
C	1.23		1.32	0.048		0.051
D	2.40		2.72	0.094		0.107
D1		1.27			0.050	
E	0.49		0.70	0.019		0.027
F	0.61		0.88	0.024		0.034
F1	1.14		1.70	0.044		0.067
F2	1.14		1.70	0.044		0.067
G	4.95		5.15	0.194		0.203
G1	2.4		2.7	0.094		0.106
H2	10.0		10.40	0.393		0.409
L2		16.4			0.645	
L4	13.0		14.0	0.511		0.551
L5	2.65		2.95	0.104		0.116
L6	15.25		15.75	0.600		0.620
L7	6.2		6.6	0.244		0.260
L9	3.5		3.93	0.137		0.154
DIA.	3.75		3.85	0.147		0.151



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